

Title (en)

AQUEOUS ALCALINE BATH FOR CHEMICALLY PLATING COPPER OR NICKEL

Publication

EP 0152601 B1 19881207 (DE)

Application

EP 84115513 A 19841215

Priority

DE 3404270 A 19840204

Abstract (en)

[origin: US4720404A] An aqueous alkaline bath is disclosed, for the adhesive chemical (electroless) deposition of copper, nickel, cobalt or their alloys with great purity, containing compounds of these metals, reducing agent, wetting agent, pH-regulating substance, stabilizer, inhibitor and complex former, characterized in that polyols and/or compounds of the biuret type are contained as complex former, as well as a method for the adhesive chemical deposition of the metals, employing this bath at a temperature from 5 DEG C. up to the boiling point of the bath, particularly for the manufacture of printed circuits.

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IPC 8 full level

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CPC (source: EP US)

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